

ABSTRACT OF THE DISCLOSURE

A housing for enclosing an electronic element of an electronic device is provided. The housing is formed of plastic material without electromagnetic waves shielding capability and comprises a first hole for injecting fluid of
5 nonconductive, non-corrosive, and high heat transfer capability (e.g., silicon oil or hydro oil) or a semisolid substance having similar properties thereinto, a second hole for evacuating air, and two stop members inserted in the holes for sealing after the injection. The electronic element is adapted to be waterproof and vibration-proof, and has a predetermined heat dissipation capability.

10